

# SOT1799-6

CFM6F, ceramic flange mount flat package; 6 terminals; 4.445 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

9 July 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	CFM6F
<b>Package style descriptive code</b>	CFMF (ceramic flange mount flat)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-08-2018
<b>Manufacturer package code</b>	98ASA01208D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.65	9.78	9.91	mm
package width	20.45	20.58	20.7	mm
package height	3.18	3.75	4.32	mm
nominal pitch	-	4.445	-	mm
actual quantity of termination	-	6	-	



CFM6F, ceramic flange mount flat package; 6 terminals; 4.445 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

2 Package outline

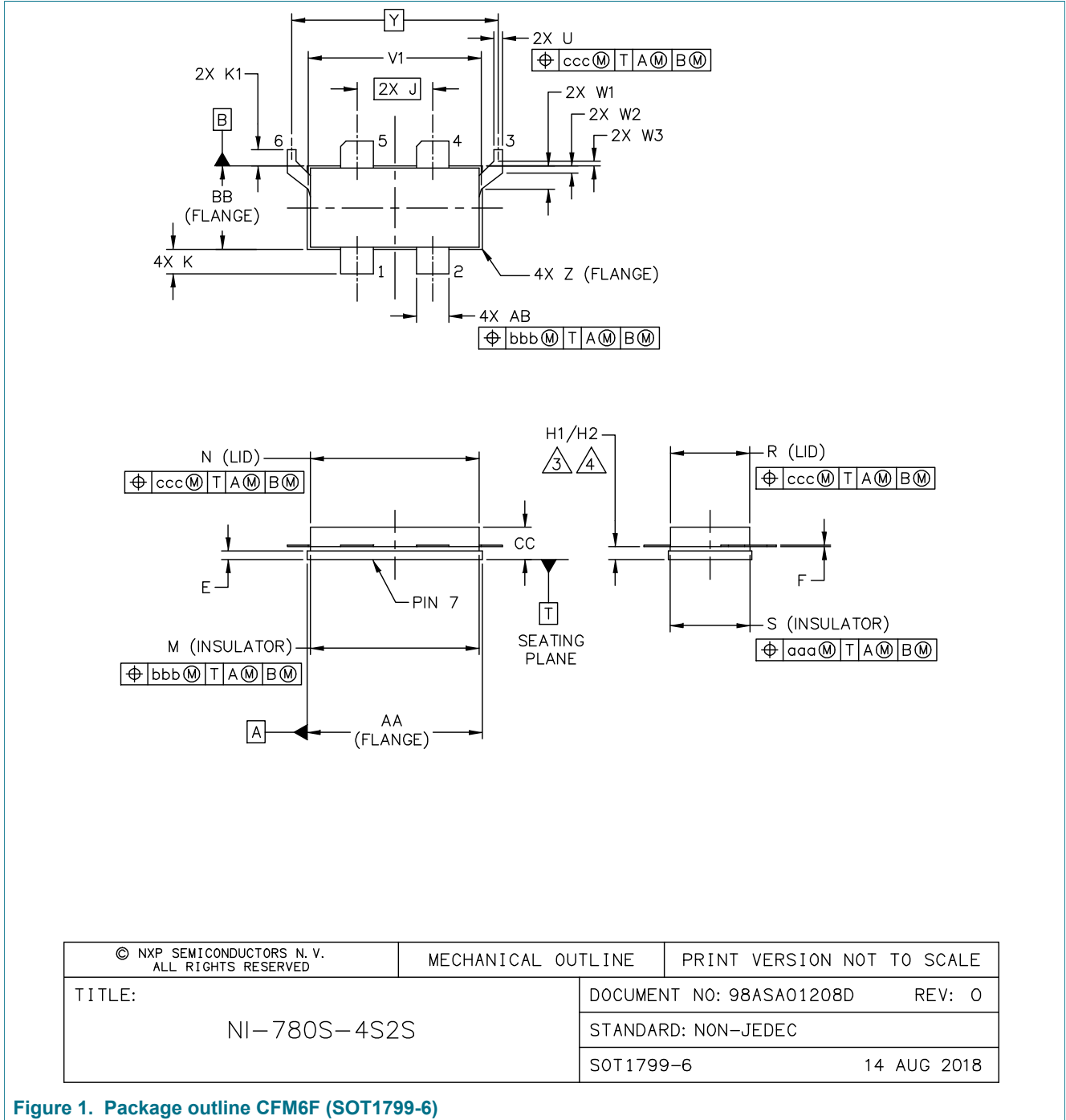


Figure 1. Package outline CFM6F (SOT1799-6)

CFM6F, ceramic flange mount flat package; 6 terminals; 4.445 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS H1 AND H2 ARE MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT. H1 APPLIES TO PINS 1, 2, 4 & 5. H2 APPLIES TO PINS 3 & 6.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	R	.365	.375	9.27	9.53
BB	.380	.390	9.65	9.91	S	.365	.375	9.27	9.53
CC	.125	.170	3.18	4.32	U	.035	.045	0.89	1.14
E	.035	.045	0.89	1.14	V1	.795	.805	20.19	20.45
F	.004	.007	0.10	0.18	W1	.0975	.1175	2.48	2.98
H1	.057	.067	1.45	1.70	W2	.0225	.0425	0.57	1.08
H2	.054	.070	1.37	1.78	W3	.0125	.0325	0.32	0.83
J	.350 BSC		8.89 BSC		Y	.956 BSC		24.28 BSC	
K	.0995	.1295	2.53	3.29	Z	R.000	R.040	R0.00	R1.02
K1	.070	.090	1.78	2.29	AB	.145	.155	3.68	3.94
M	.774	.786	19.66	19.96	aaa	.005		0.13	
N	.772	.788	19.61	20.02	bbb	.010		0.25	
					ccc	.015		0.38	

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE:  NI-780S-4S2S			DOCUMENT NO: 98ASA01208D      REV: 0		
			STANDARD: NON-JEDEC		
			SOT1799-6		14 AUG 2018

Figure 2. Package outline note CFM6F (SOT1799-6)

### 3 Legal information

---

#### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

---

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4